



PANDA Collaboration Meeting



Sezione di Torino

Pixel readout status report

G.Mazza

on behalf of the MVD Torino group



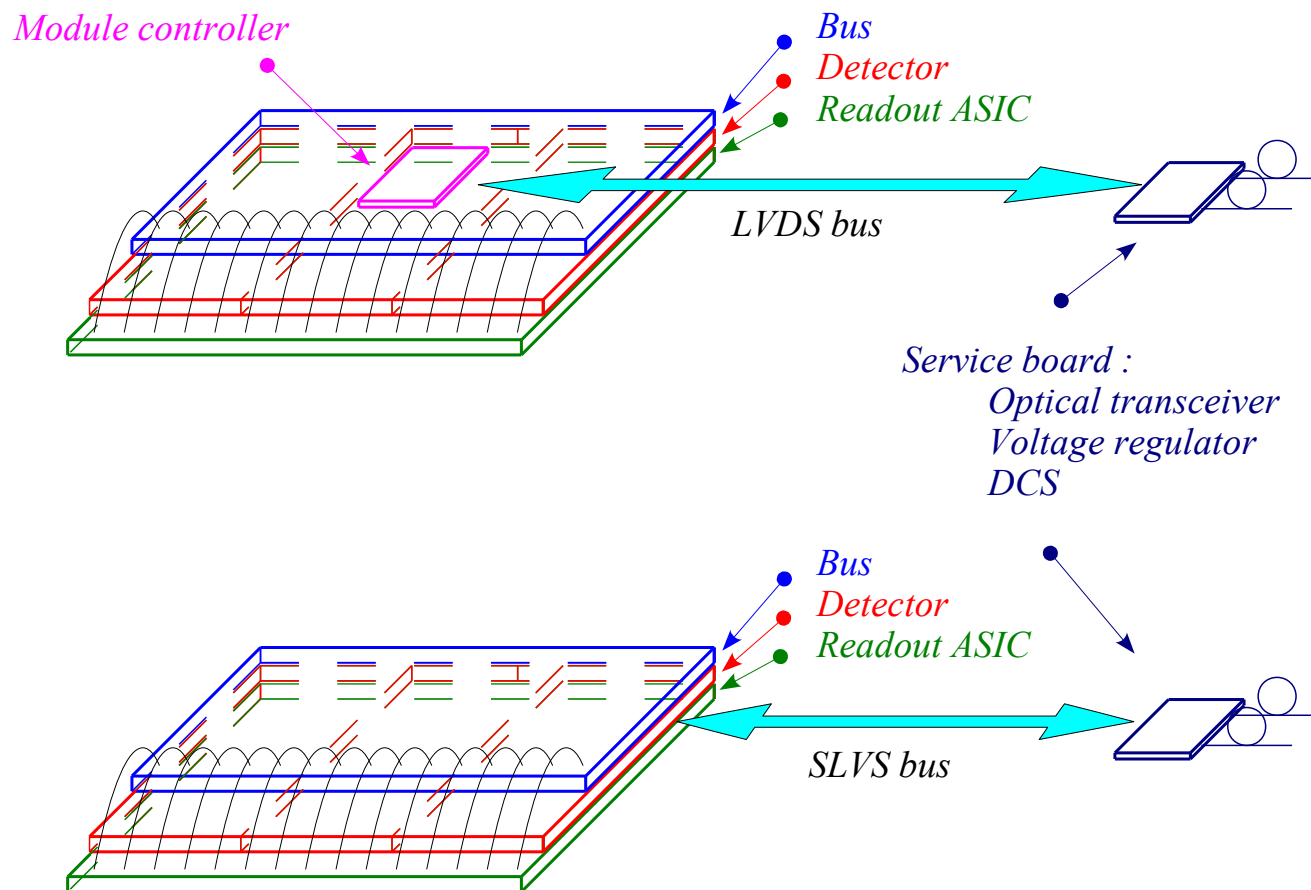
Pixel specs



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<i>Pixel size</i>	$100 \times 100 \mu\text{m}^2$
<i>Chip active area</i>	$11.4 \times 11.6 \text{ mm}^2$ (116 rows, 110 cols)
<i>dE/dx measurement</i>	ToT, 12 bits dynamic range
<i>Max input charge</i>	50 fC
<i>Noise floor</i>	$< 32 \text{ aC}$ (200 e^-)
<i>Clock frequency</i>	155.52 MHz
<i>Time resolution</i>	6.45 ns (1.9 ns r.m.s.)
<i>Power consumption</i>	$< 750 \text{ mW/cm}^2$
<i>Max event rate</i>	$6 \cdot 10^6$
<i>Total ionizing dose</i>	$< 100 \text{ kGy}$

Readout scheme



Option 1

Option 2



ToPiX v3



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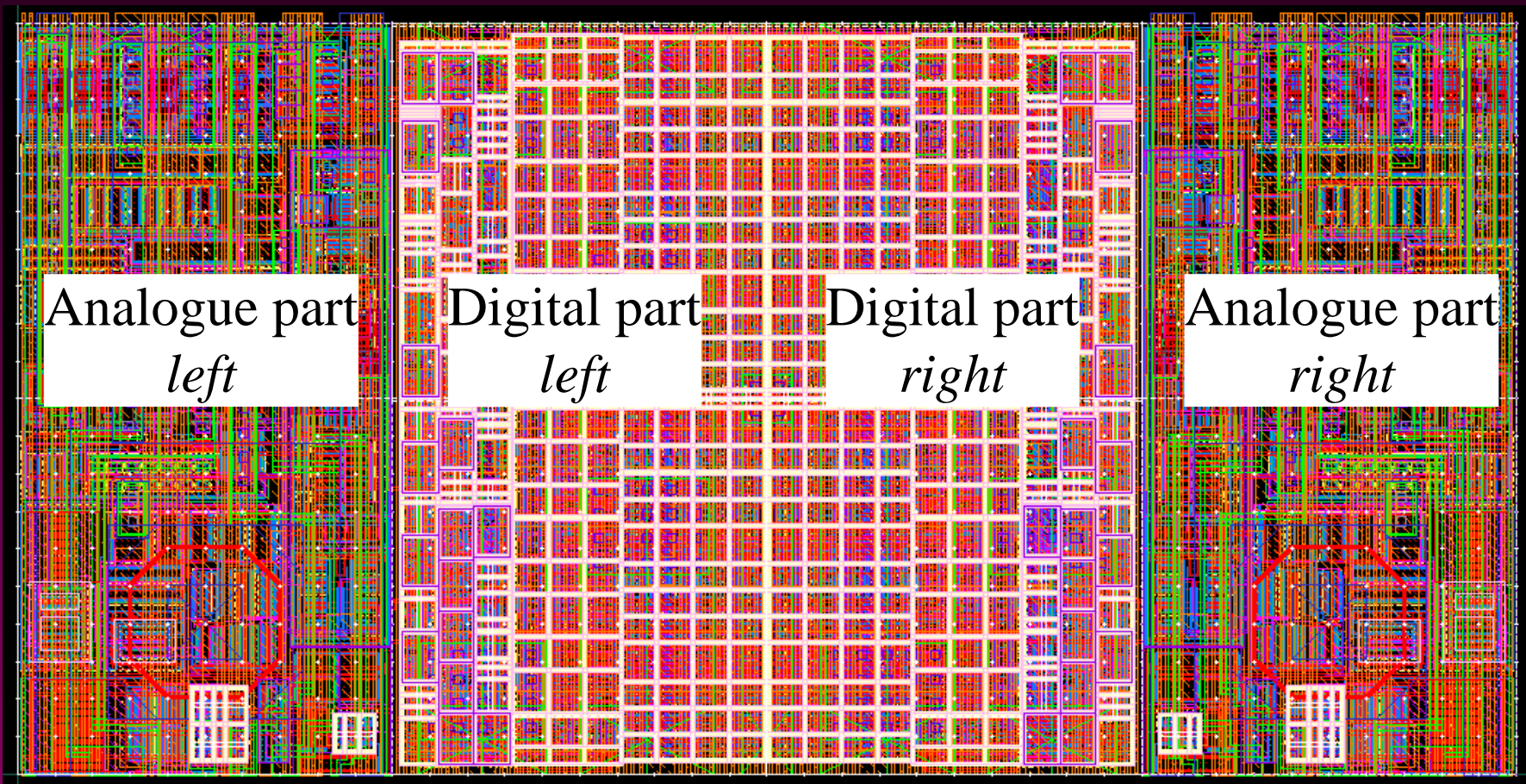
- Layout submitted on February 7th – received May 16th
- 4.5x4 mm² die area
- CMOS 0.13 μm DM technology
- Triple redundancy-based SEU protection
- End of column logic
- 160 Mb/s SLVS serial output
- Pads for bump bonding



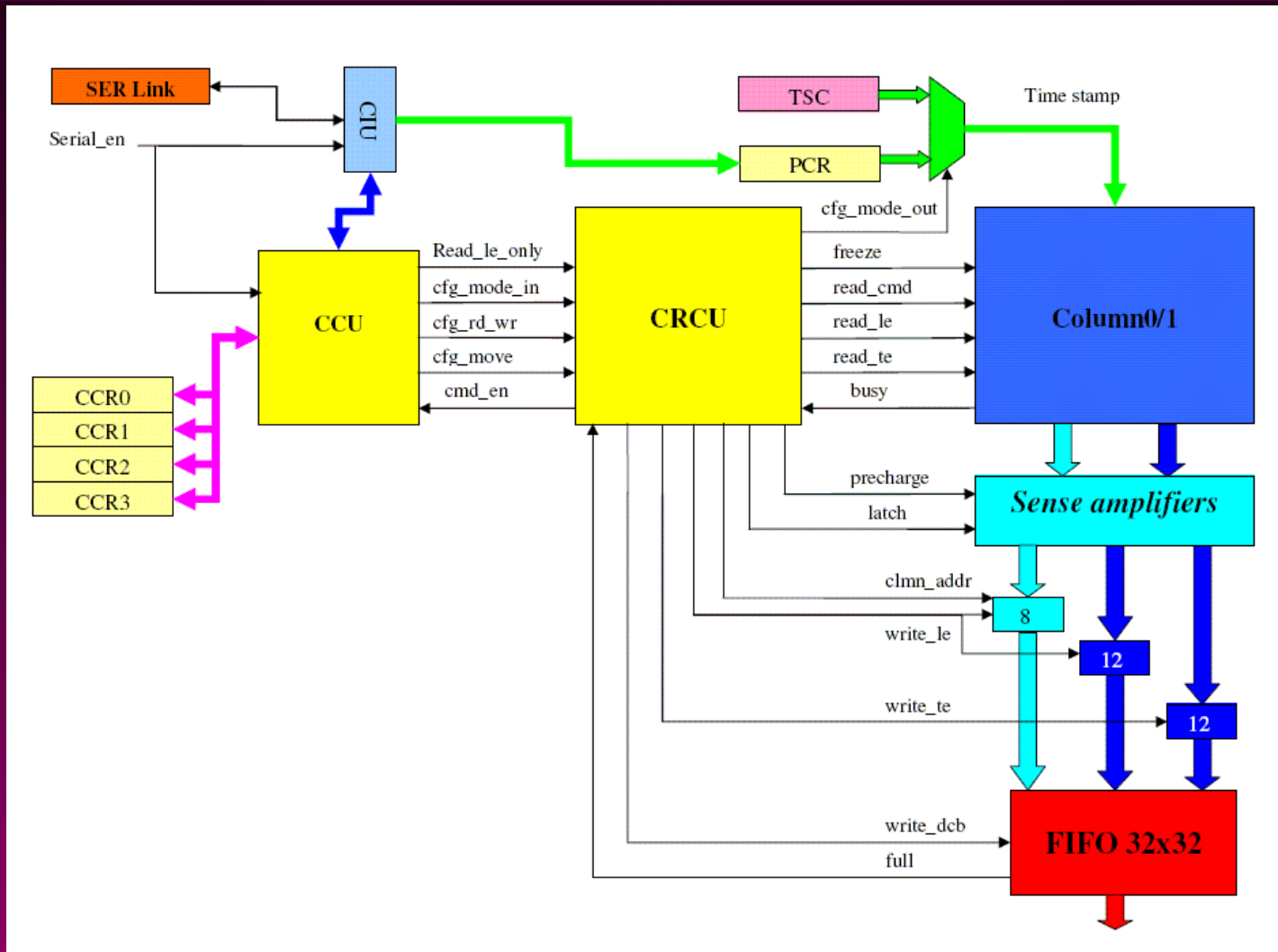
Double cell



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Common bus

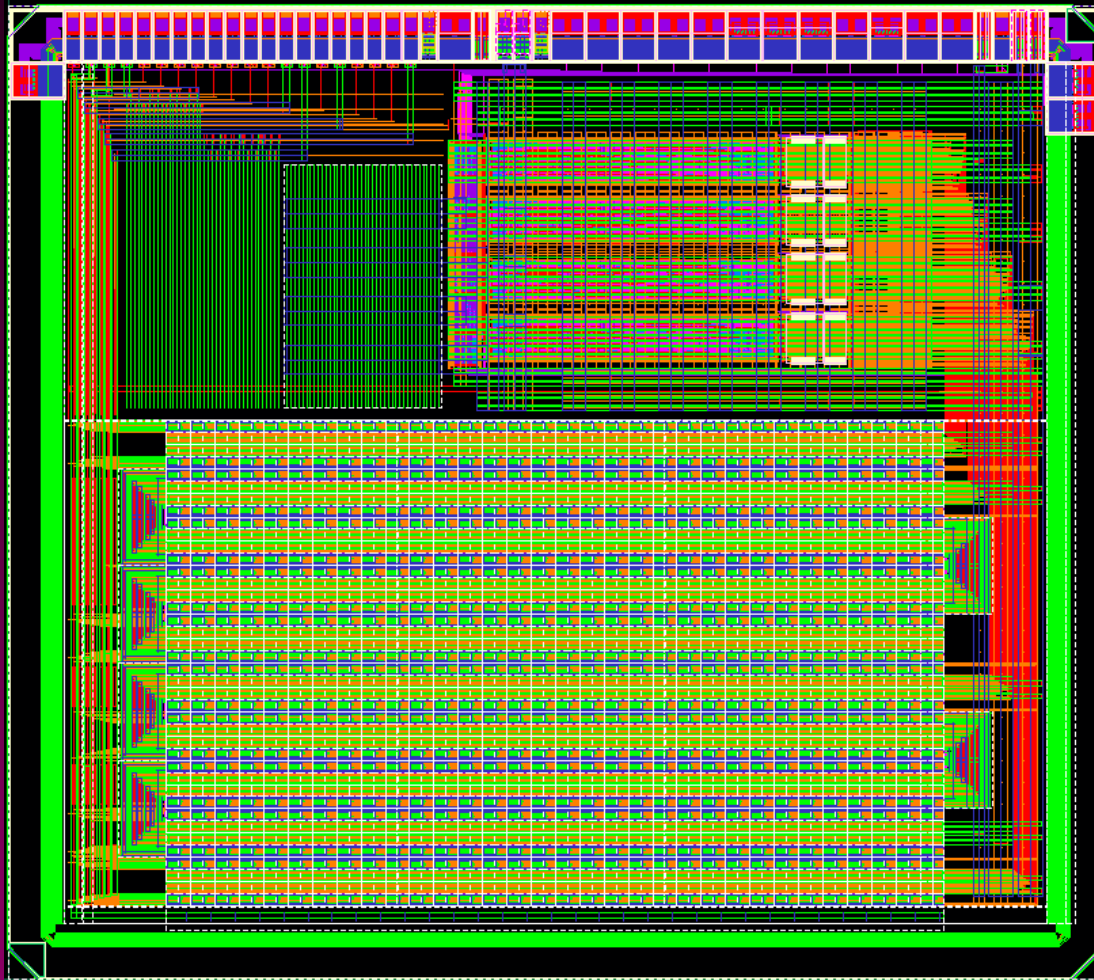




ToPiX v3 layout



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- * 4.5 mm × 4 mm
- * CMOS 130 nm
- * Clock frequency 160 MHz
- * bump bonding pads
- * 2×2×128 columns
- * 2×2×32 columns
- * 32 cells EoC FIFO
- * SEU protected EoC
- * Serial data output
- * SLVS I/O



ToPiX v3 test status



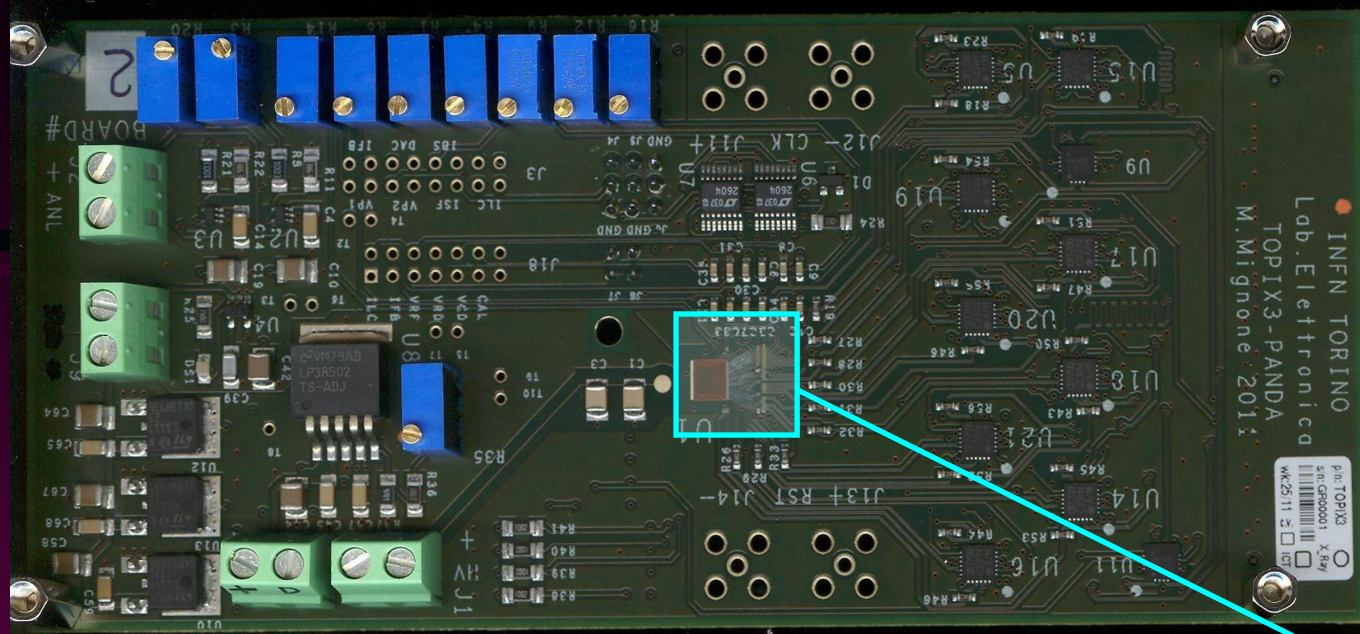
- * Four chips (without sensors) mounted
- * At 160MHz can only read and program first ~32 pixels of each column
- * At 50MHz (with pre-emphasis disabled) full operation
- * S-curve working well (programmable internal test pulse)
- * Baseline measurements ok
- * On-pixel DACs characterised and correction applied
- * Optimisation of analogue parameters ongoing but likely to change significantly with sensor assemblies
- * Acquisition system is working (4 boards)



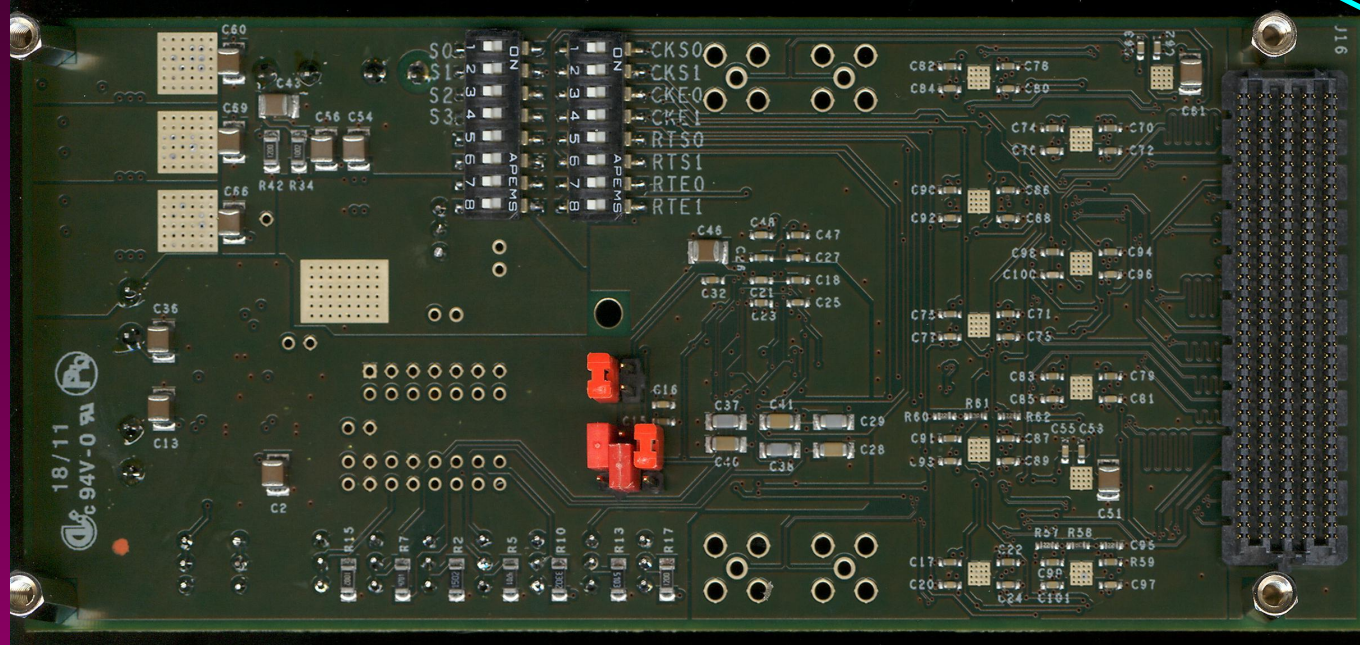
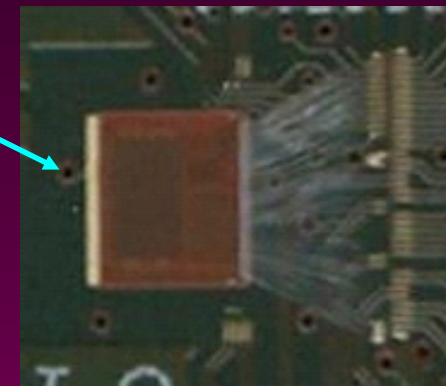
Clock frequency problem

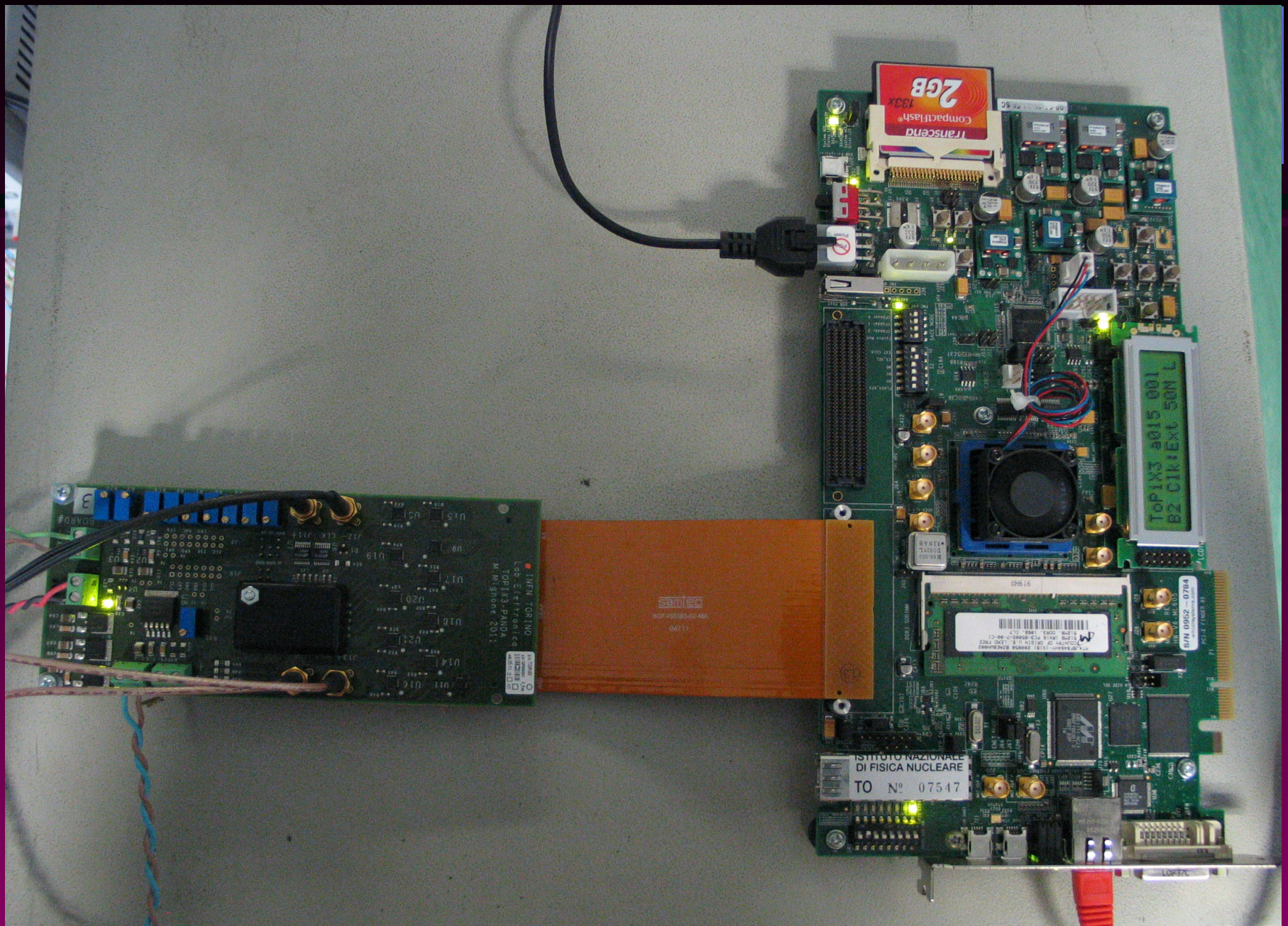


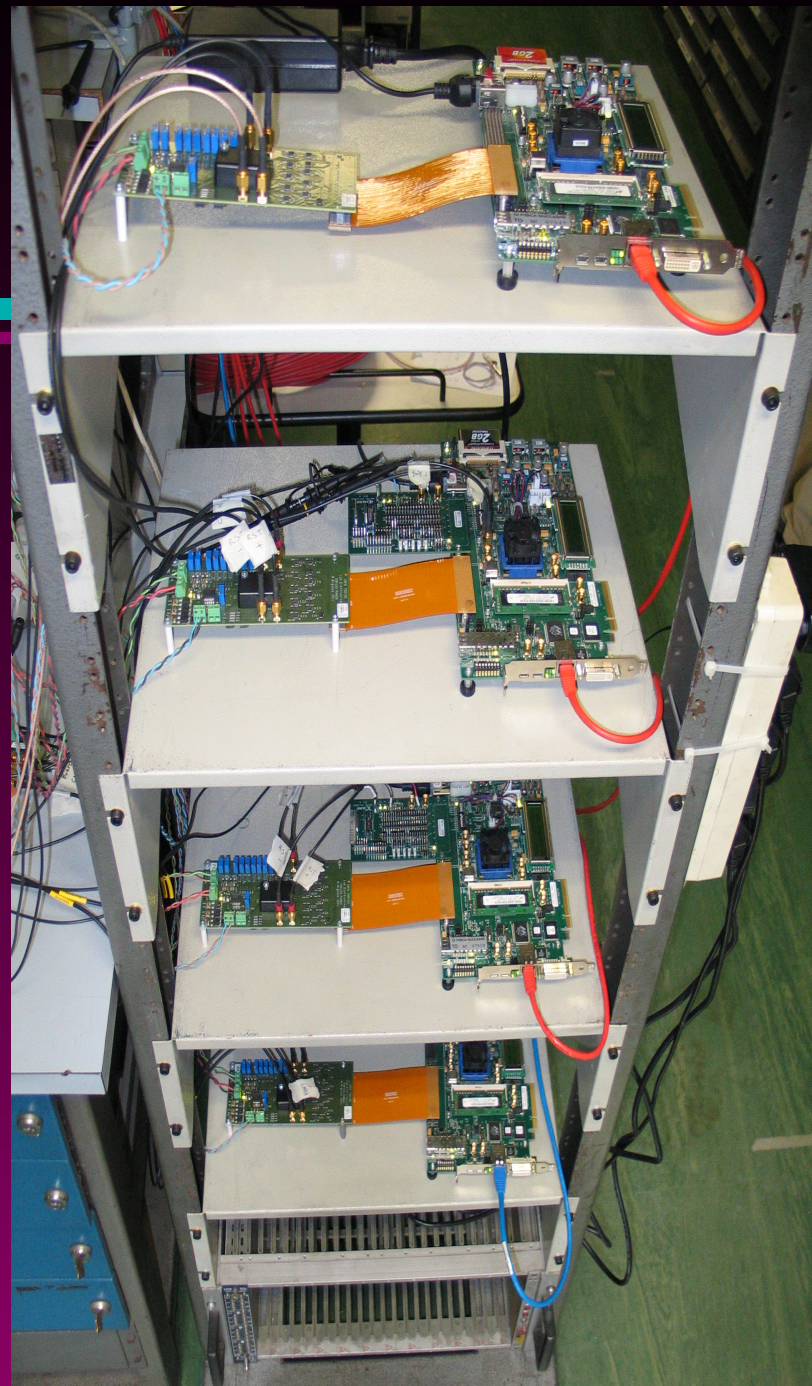
- * At 160 MHz only the first 32 pixels of the 128 cells columns work correctly
- * Response improves when the frequency is decreased
- * Prototype full column has 30% longer bus and 10% more cells than the final chip
 - *unfortunately this is not sufficient*
- * better simulation model for the bus is required
- * column readout can be slowed down with no significant effects
- * new bus driver architecture required ?



ToPiX v3









Functional tests @ 50 MHz

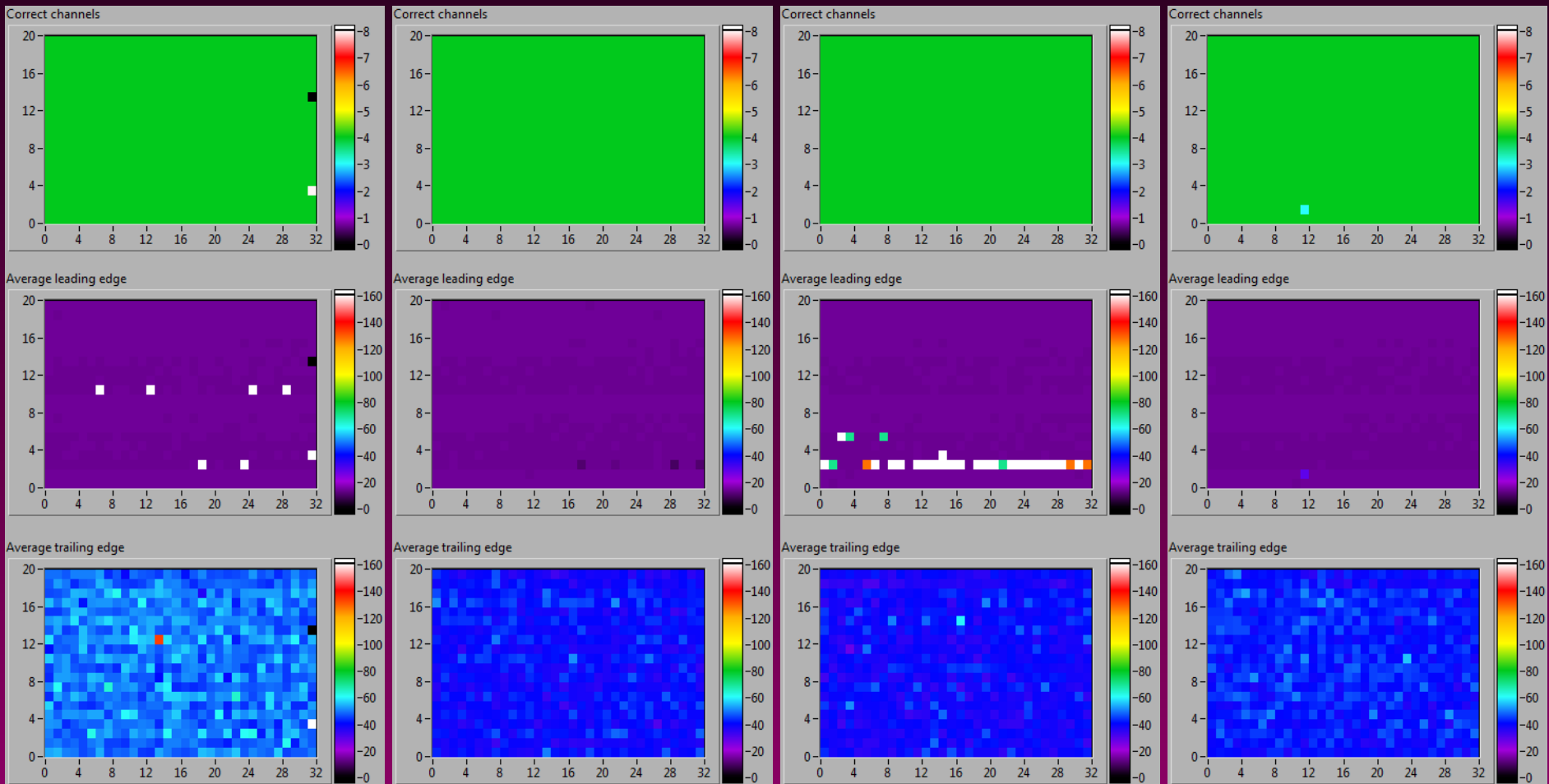


Chip 1

Chip 2

Chip 3

Chip 4



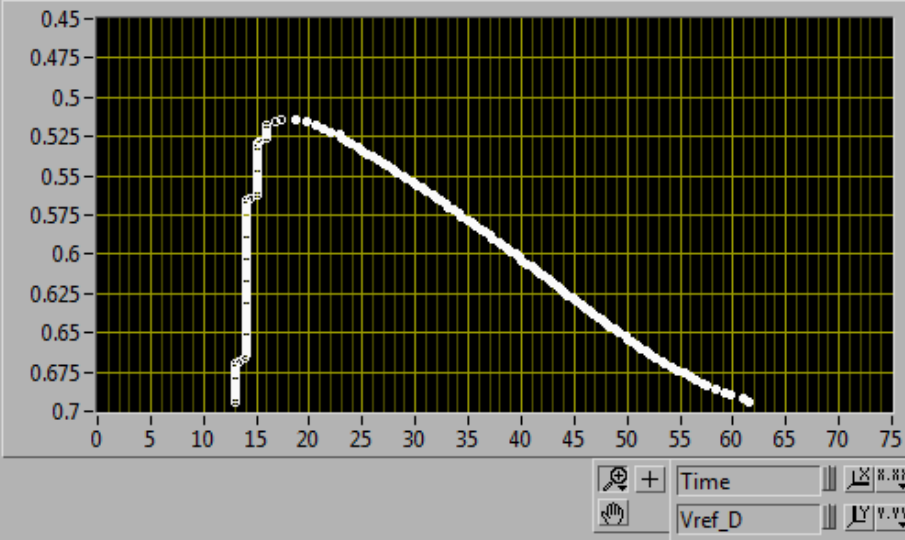


Signal shape

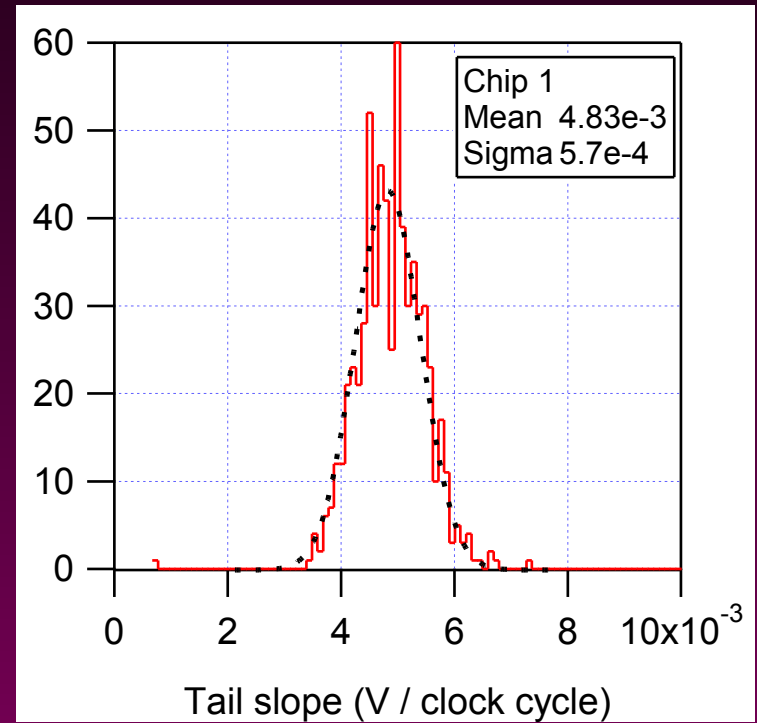
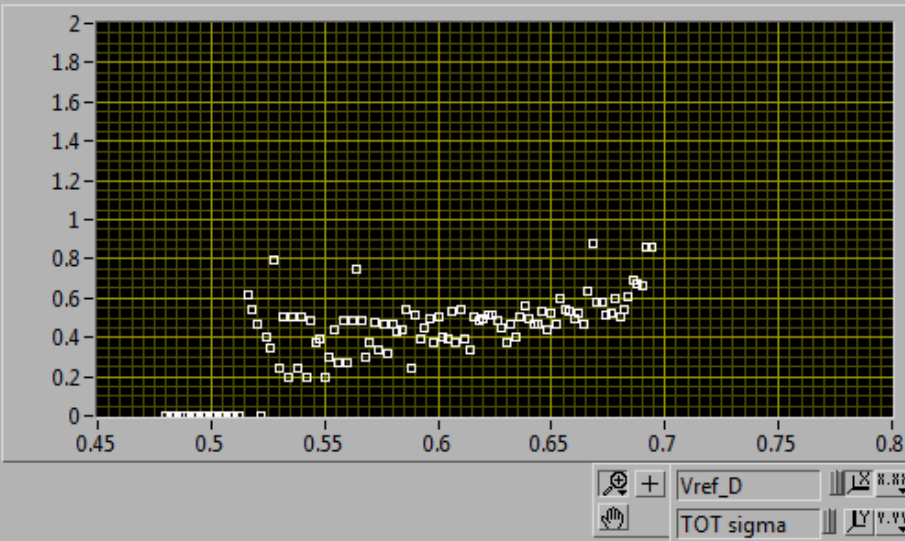


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Signal shape

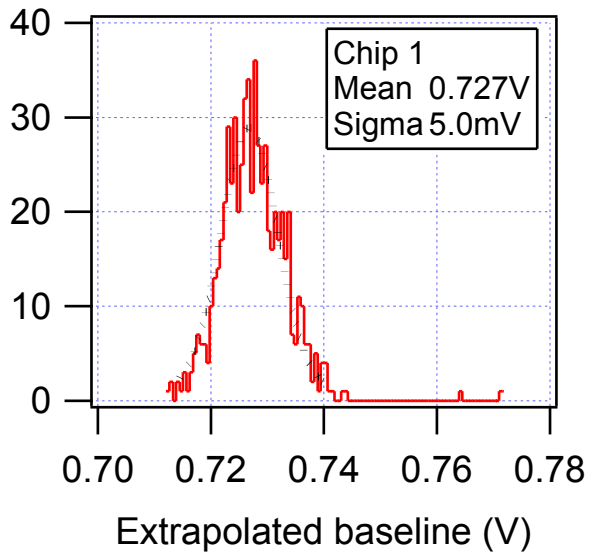
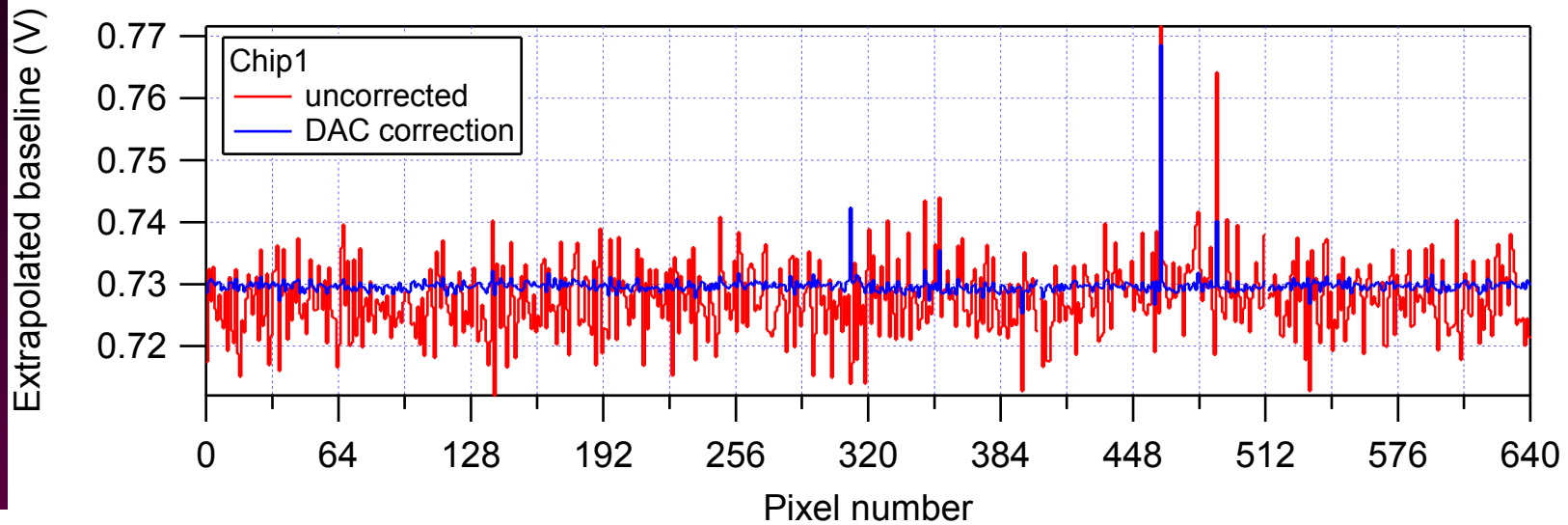


TOT sigma

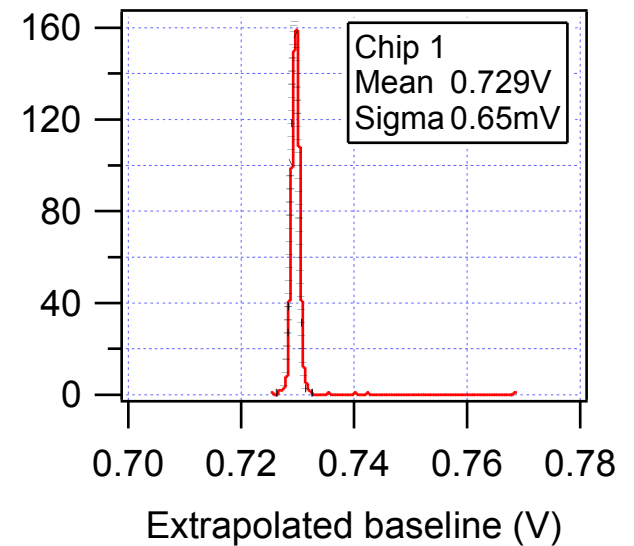


4.14 ns/mV
274 ns/fC

Baseline correction

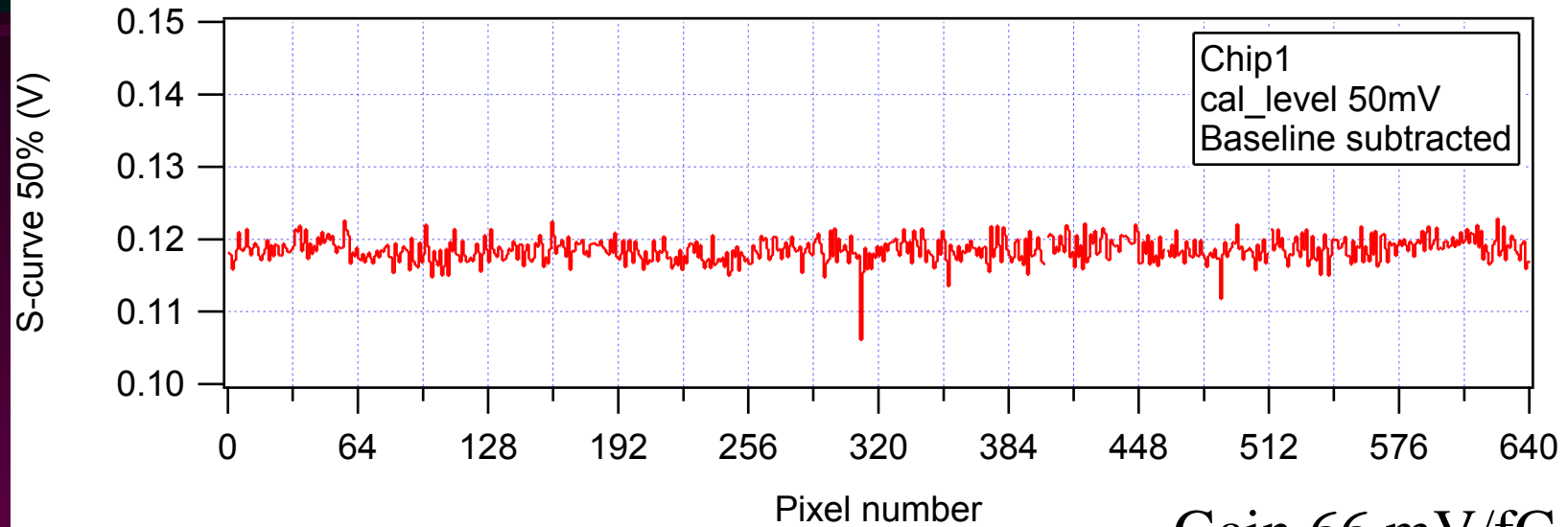


*DAC
correction*

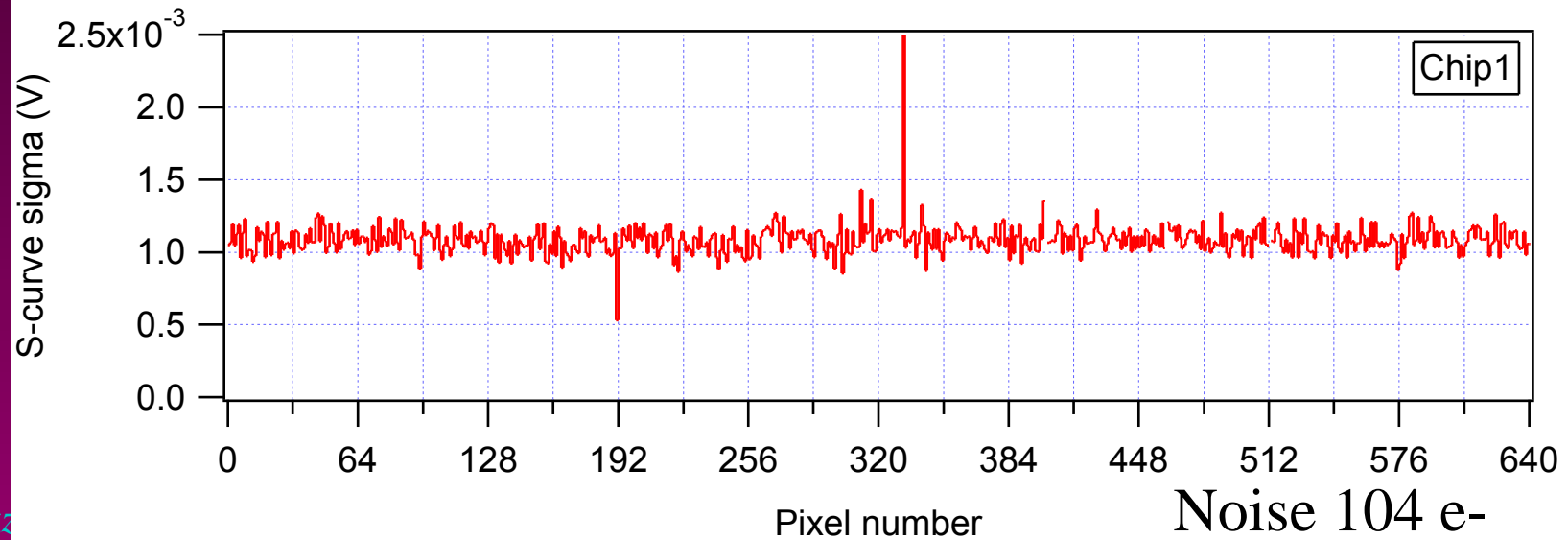




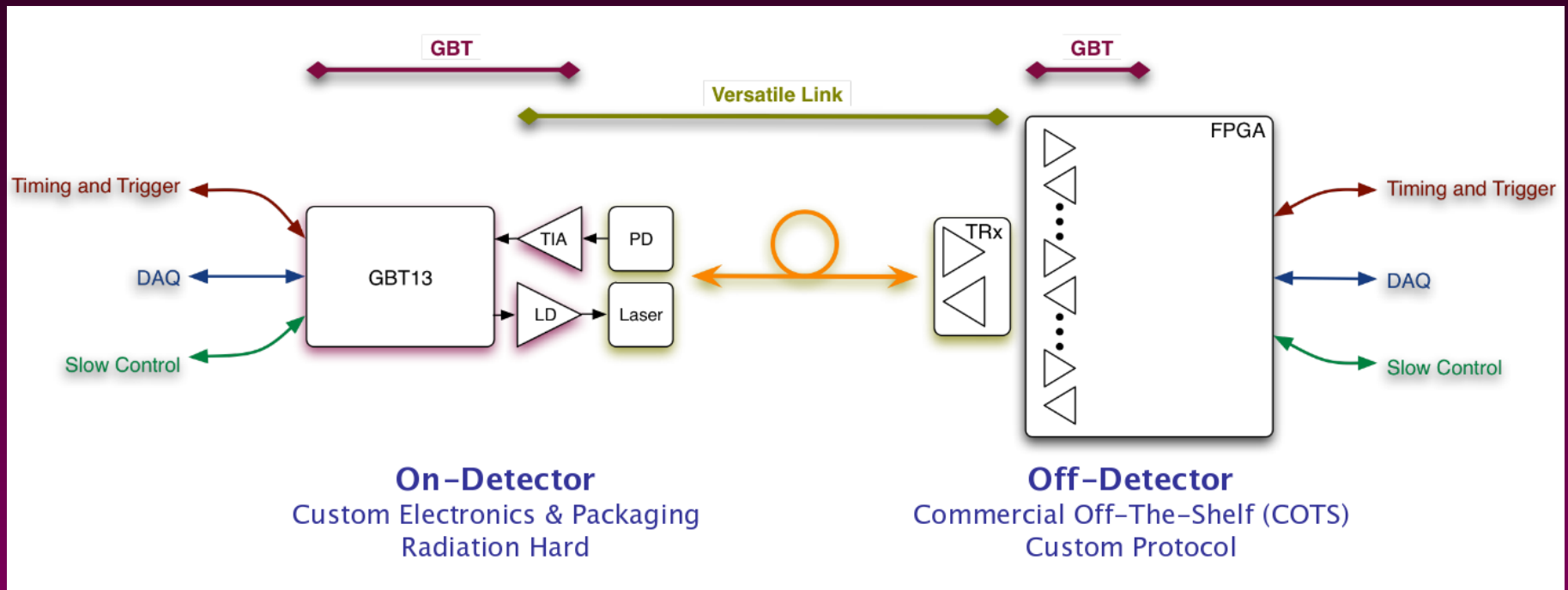
Gain & Noise



Gain 66 mV/fC



Noise 104 e-





GBT chipset



Radiation tolerant chipset :

- * GBTIA : Transimpedance optical receiver
- * GBLD : Laser driver
- * GBTx : Data and Timing Transceiver
- * GBT-SCA : Slow control ASIC

Target Applications :

- * Data readout
- * TTC
- * Slow control and monitoring links

Supports :

- * Bidirectional data transmission
- * Bandwidth :
 - Line rate : 4.8 Gb/s
 - Effective : 3.36 Gb/s

Radiation Tolerance :

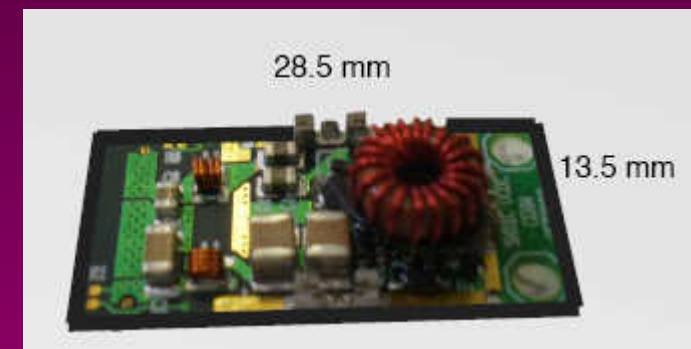
- * Total dose
- * Single Event Upset



Power regulator



- * ToPiX power supply $1.2 \text{ V} - I_{\text{DC}} \sim 1 \text{ A}$ (estimated)
→ voltage drop on cables is not negligible
- * A DC-DC converter solution compatible with the radiation levels and the magnetic field of a silicon tracker is under development @ CERN for sLHC
- * Current CERN version : $V_{\text{IN}} 10 \div 12 \text{ V}$, $V_{\text{OUT}} = 1.8 \div 3.3 \text{ V}$, $I_{\text{OUT}} < 3 \text{ A}$
- * $V_{\text{OUT}} = 1.5 \text{ V}$, $I_{\text{OUT}} < 3-4 \text{ A}$ now avail.
- * Board position t.b.d.
→ *ToPiX internal regulator t.b.d.*





Conclusions



- * A pixel readout architecture has been defined – waits for more detailed rate simulations to be finalized.
- * F/E ASIC with full pixel cells and columns has been designed and tested – a new prototype, with full end of column logic is currently under test.
- * A GBT-based interface to the DAQ system is under evaluation. Contacts with the CERN GBT group ongoing.
- * Started discussion with a CERN group for radiation tolerant DC-DC converter. Solutions based on the AMIS ASIC and commercial chips are under evaluation.



Next steps



- * Test of ToPiX v3
- * Simulations of the ToPiX updated architecture with the data
← input from simulations
- * ToPiX bus modeling
- * ToPiX more accurate power estimation (from v3 tests) →
input to cooling design
- * 1st approximation definition of the data trasmission board and
the power regulator board →input to mechanical design
- * New aluminium cables testing with SLVS drivers

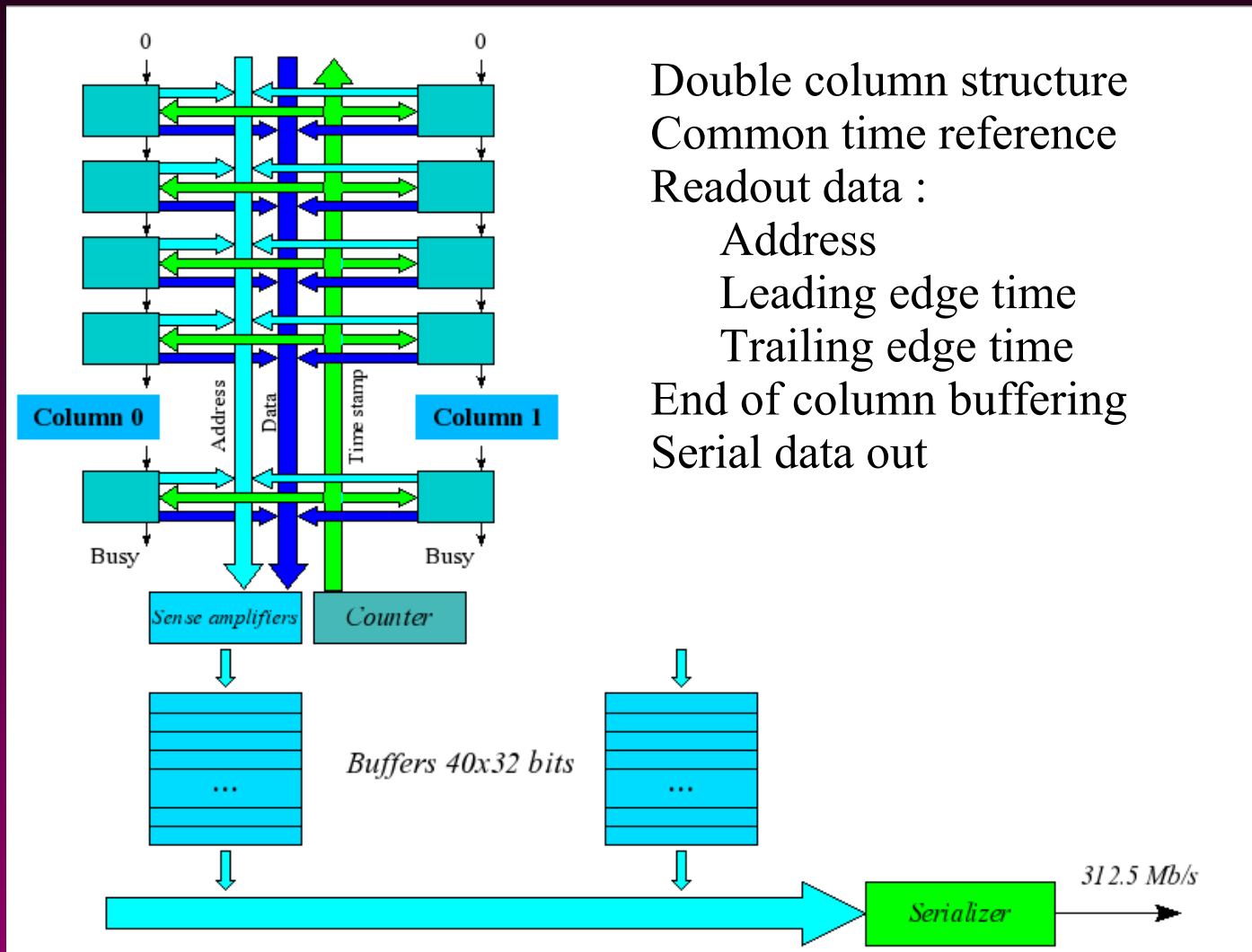


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Backup slides



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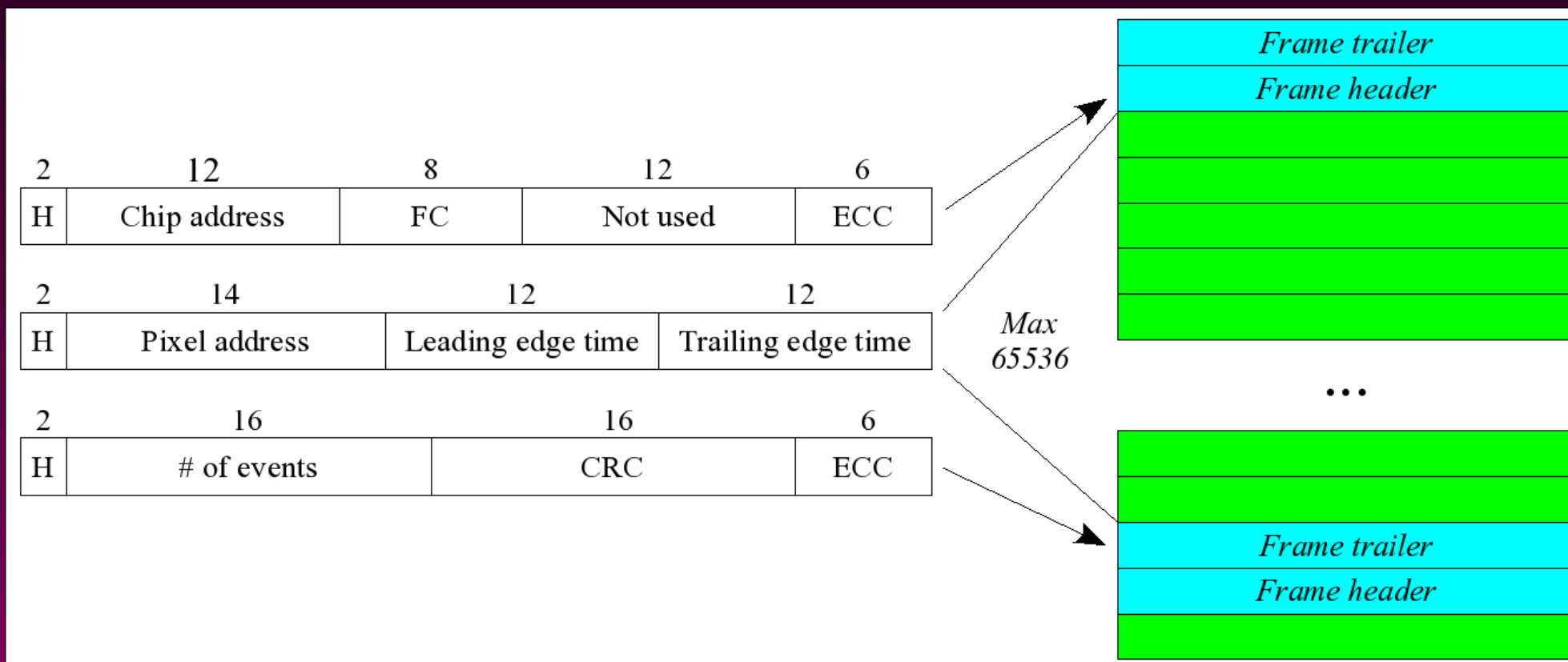




Data format



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ToPiX ASIC



- * Custom development for the PANDA MVD
- * Provides spatial and time coordinates plus energy resolution measurement (via ToT)
- * Compatible either with p-type or n-type detectors
- * Self triggered architecture
- * Each event has a 12 bits time reference
- * Double rate serial readout
- * Radiation tolerant
- * Data corresponding to a 12 bits counter cycle (26.21 μs) are packed in a frame, with an 8 bits frame counter (6.71 ms cycle)

Pixel cell

